

General Description

The MY10B04C uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

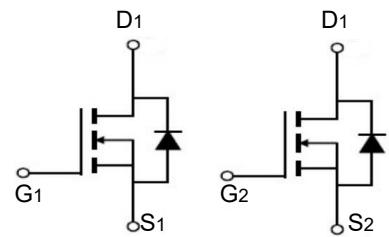
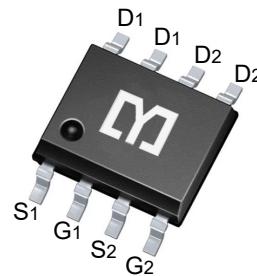


: YUh fYg

X _{FUU}	40	X
I _F	10	C
P _D (T _C =25°C)	2.1	W
T _{FRQP} (°C) U? 10X+	>16	o á

Application

- Battery Protection
- Sí a Á, á&@
- Wj á CII] cñ|A[, ^|Á^]]|^



DUM_U[Y A Ur_]b[UbX CfXYf]b[-bZfa U]cb

DfcXi Wi-B	DUM_	A Ur_]b[E lmfd7 G_L
MY10B04C	ÜUÚß	4882	HEEE

5 Vgc`i hYAU Ja i a 'FU[b[g'fH, 18) °C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	40	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	10	A
Drain Current-Continuous(T _C =100°C)	I _D (100°C)	6.4	A
Pulsed Drain Current	I _{DM}	40	A
Maximum Power Dissipation	P _D	2	W
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 To 150	°C
Thermal Resistance,Junction-to-Ambient (Note 2)	R _{θJA}	62.5	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	40	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=40\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	±100	nA
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	1	1.5	2.0	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=8\text{A}$	-	14.9	16	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=4\text{A}$	-	18.9	24	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=8\text{A}$	33	-	-	S
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=20\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1.0\text{MHz}$	-	964	-	PF
Output Capacitance	C_{oss}		-	109	-	PF
Reverse Transfer Capacitance	C_{rss}		-	96	-	PF
Turn-on Delay Time	$\text{t}_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=20\text{V}, \text{R}_{\text{L}}=2.5\Omega$ $\text{V}_{\text{GS}}=10\text{V}, \text{R}_{\text{GEN}}=3\Omega$	-	5.5	-	nS
Turn-on Rise Time	t_{r}		-	14	-	nS
Turn-Off Delay Time	$\text{t}_{\text{d}(\text{off})}$		-	24	-	nS
Turn-Off Fall Time	t_{f}		-	12	-	nS
Total Gate Charge	Q_{g}	$\text{V}_{\text{DS}}=20\text{V}, \text{I}_D=8\text{A}, \text{V}_{\text{GS}}=10\text{V}$	-	22.9	-	nC
Gate-Source Charge	Q_{gs}		-	3.5	-	nC
Gate-Drain Charge	Q_{gd}		-	5.3	-	nC
Diode Forward Voltage ^(Note 3)	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_S=9\text{A}$	-	0.8	1.2	V

Typical Characteristics

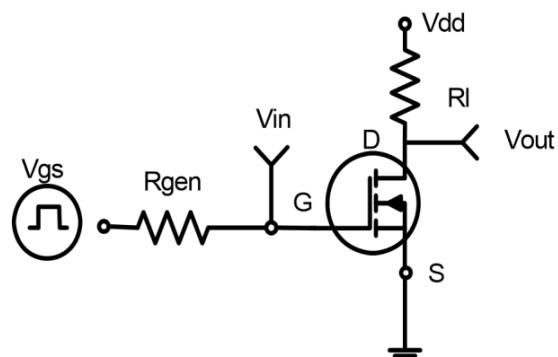


Figure 1:Switching Test Circuit

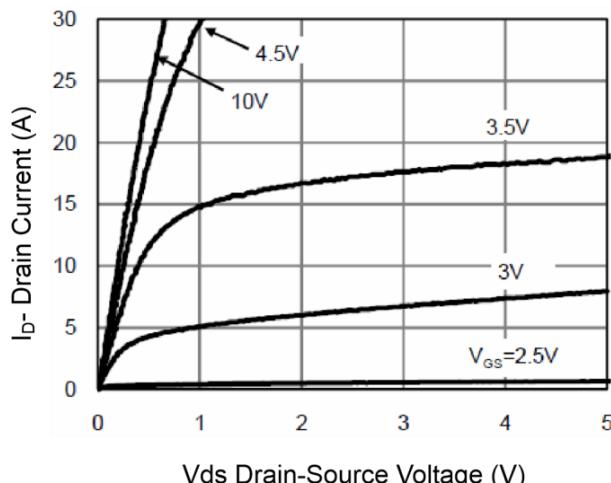


Figure 3 Output Characteristics

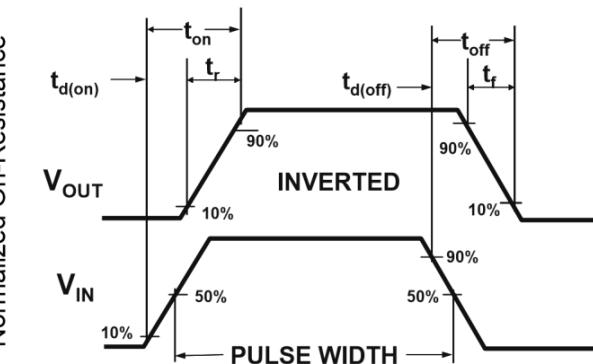
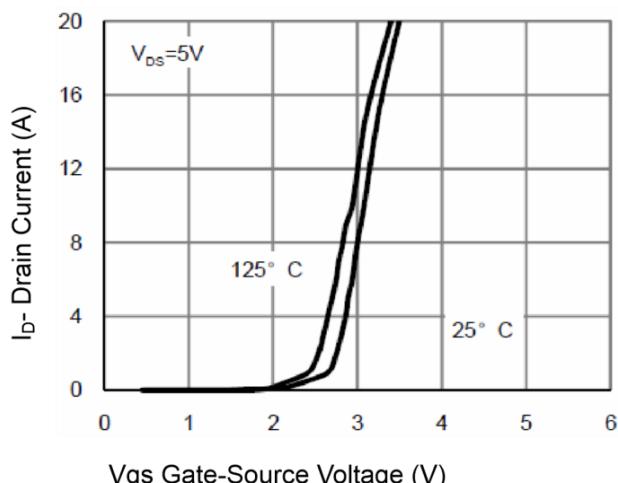


Figure 2:Switching Waveforms



V_{DS}=5V

125° C
25° C

Figure 4 Transfer Characteristics

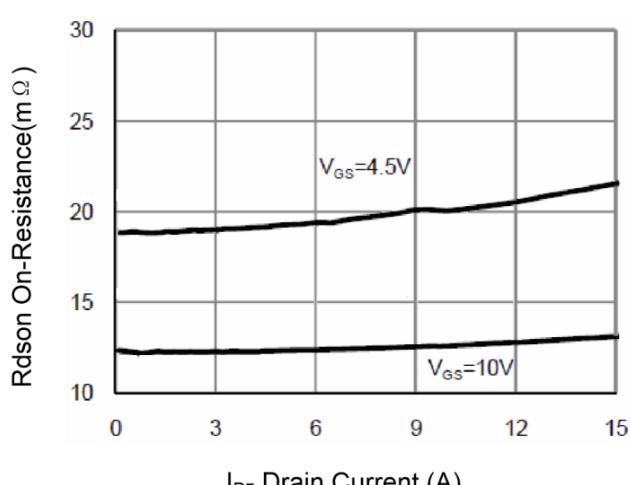


Figure 5 Drain-Source On-Resistance

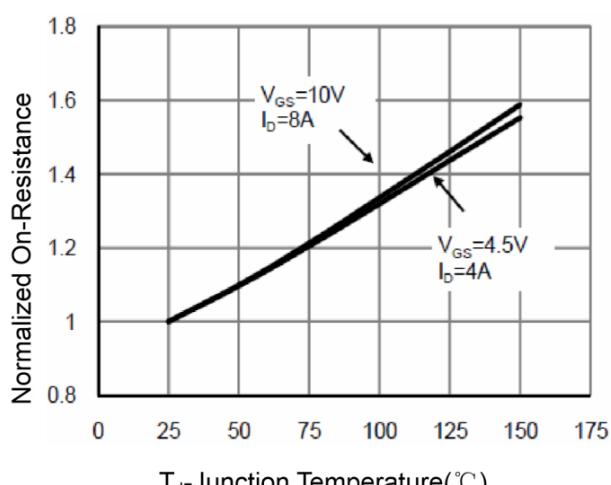


Figure 6 Drain-Source On-Resistance

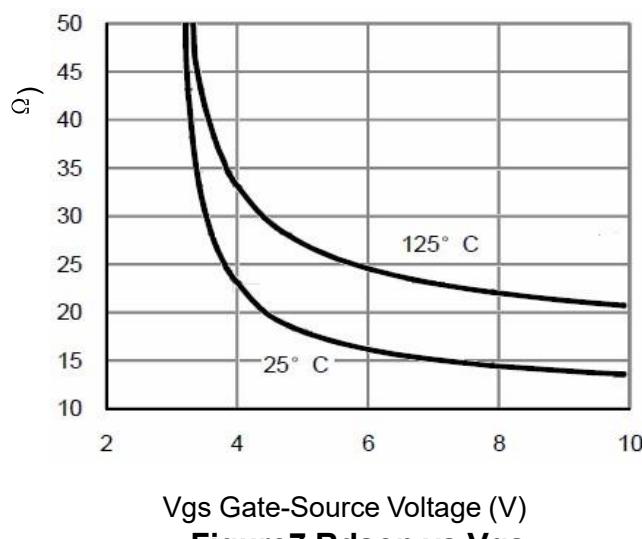


Figure 7 Rdson vs Vgs

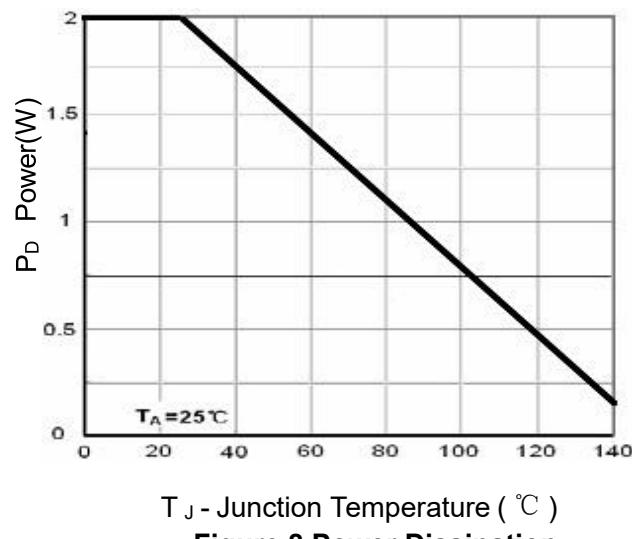


Figure 8 Power Dissipation

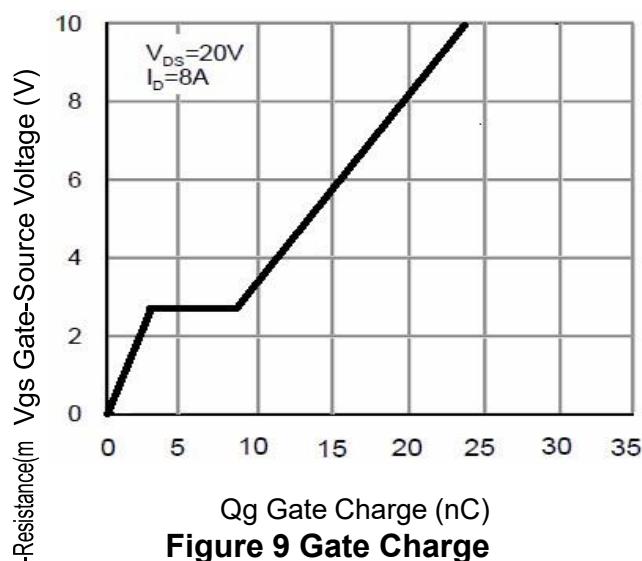


Figure 9 Gate Charge

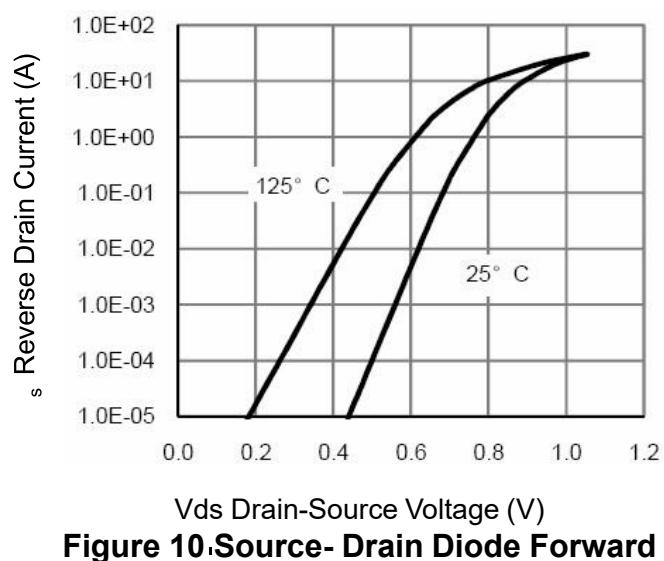


Figure 10 Source-Drain Diode Forward

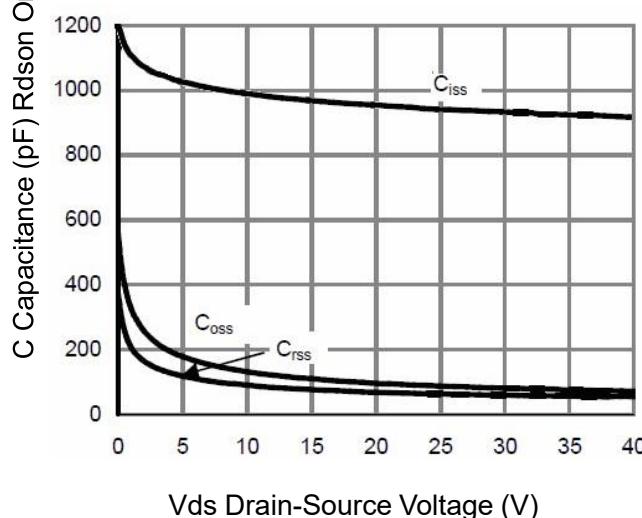


Figure 11 Capacitance vs Vds

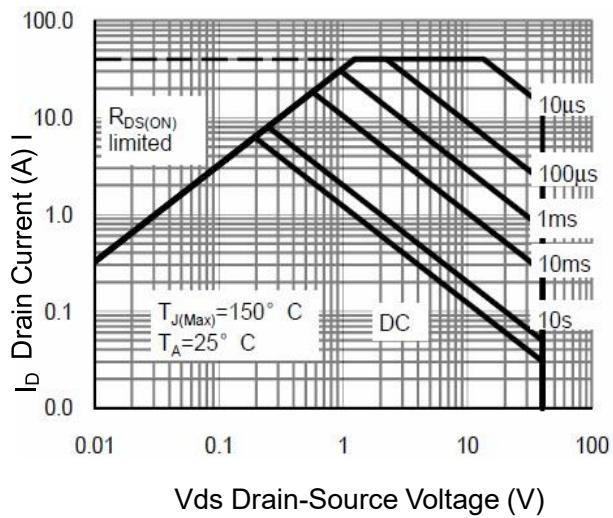
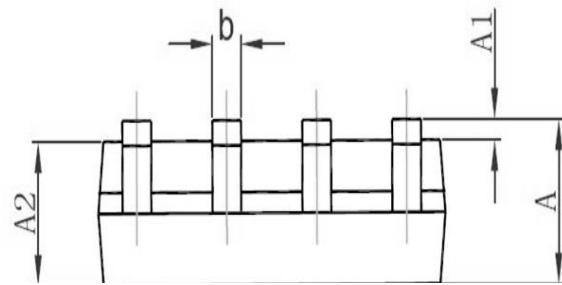
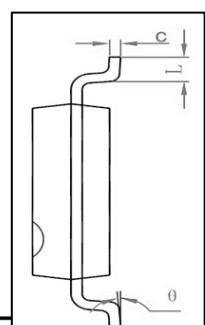
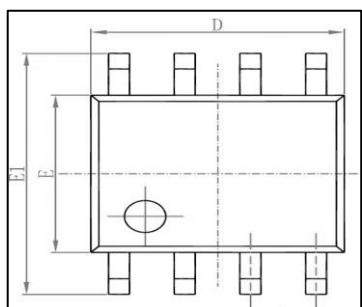
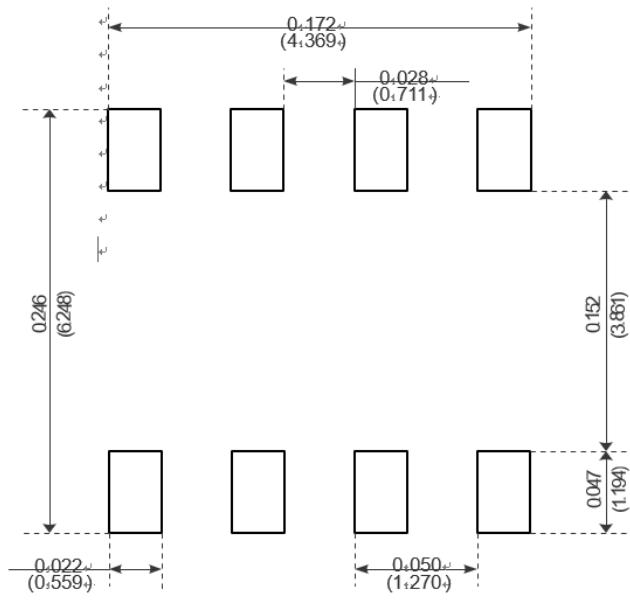


Figure 12 Safe Operation Area

Package Mechanical Data-SOP-8



Symbol	Dimensions in Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Recommended Minimum Pads